

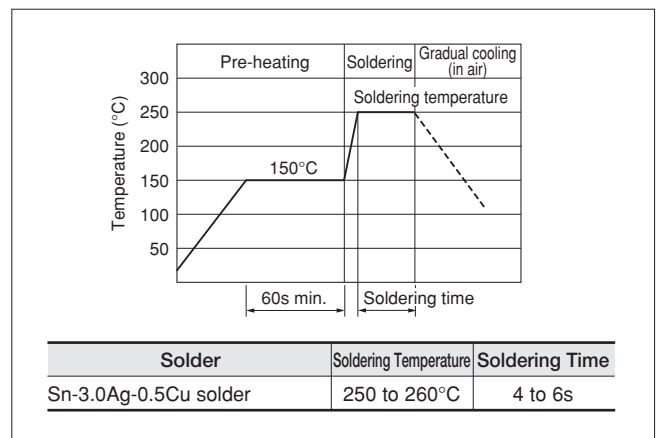
## 1. Mounting Hole

Mounting holes should be designed as specified below.

Part Number	Bulk Type (in mm)	Taping Type (in mm)
DSN6 DSS6 VFR3V VFS6V DSS1		
DSN9 DSN9H		
DST9 DST9H		
VFS9V		
VFC2H		

## 2. Soldering

- Use Sn-3.0Ag-0.5Cu solder.
- Use Rosin-based flux. Do not use strong acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).
- Products and the leads should not be subjected to any mechanical stress during the soldering process, or while subjected to the equivalent high temperatures.
- Standard flow soldering profile.



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### 3. Cleaning Conditions

Do not clean VFR3V, PLT09H and VFS6V series.

Clean other parts in the following conditions.

(1) Cleaning temperature should be limited to 60°C max.  
(40°C max for alcohol type cleaner).

(2) Ultrasonic cleaning should comply with the following conditions, avoiding the resonance phenomenon at the mounted products and PCB.

Power: 20 W / ℓ max. Frequency: 28 to 40kHz

Time: 5 min. max.

(3) Cleaner

(a) Alcohol type cleaner

Isopropyl alcohol (IPA)

(b) Aqueous agent (PLT series cannot be cleaned)

PINE ALPHA ST-100S

(4) There should be no residual flux or residual cleaner left after cleaning.

In the case of using aqueous agent, products should be dried completely after rinsing with de-ionized water in order to remove the cleaner.

(5) The surface of products may become dirty after cleaning, but there is no deterioration on mechanical, electrical characteristics and reliability.

(6) Other cleaning: Please contact us.